

June 1999 File Number 2880.2

4A, 50V and 60V, 0.800 Ohm, N-Channel Power MOSFETs

These are N-Channel enhancement mode silicon gate power field effect transistors designed for applications such as switching regulators, switching converters, motor drivers, relay drivers and drivers for high power bipolar switching transistors requiring high speed and low gate drive power. These types can be operated directly from integrated circuits.

Formerly developmental type TA09378.

Ordering Information

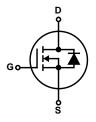
PART NUMBER	PACKAGE	BRAND		
RFP4N05	TO-220AB	RFP4N05		
RFP4N06	TO-220AB	RFP4N06		

NOTE: When ordering, include the entire part number.

Features

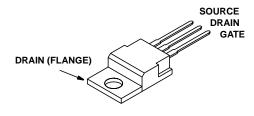
- 4A, 50V and 60V
- $r_{DS(ON)} = 0.800\Omega$
- · Related Literature
 - TB334 "Guidelines for Soldering Surface Mount Components to PC Boards"

Symbol



Packaging

JEDEC TO-220AB



RFP4N05, RFP4N06

Absolute Maximum Ratings $T_C = 25^{\circ}C$, Unless Otherwise Specified

	RFP4N05	RFP4N06	UNITS
Drain to Source Voltage (Note 1)V _{DSS}	50	60	V
Drain to Gate Voltage (RGS = $20k\Omega$) (Note 1)V _{DGR}	50	60	V
Drain Current, RMS Continuous	4	4	Α
Pulsed Drain Current (Note 3)	10	10	Α
Gate to Source Voltage	±20	±20	V
Maximum Power Dissipation	25	25	W
Linear Derating Factor	0.2	0.2	W/ °C
Operating and Storage Temperature	-55 to 150	-55 to 150	oC
Maximum Temperat6ure for Soldering			
Leads at 0.063in (1.6mm) from Case for 10sT _L	300	300	°С
Package Body for 10s, See Techbrief 334	260	260	оС

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. $T_J = 25^{\circ}C$ to $125^{\circ}C$.

$\textbf{Electrical Specifications} \hspace{0.3cm} \textbf{T}_{C} = 25^{o}\text{C, Unless Otherwise Specified}$

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Drain to Source Breakdown Voltage RFP4N05	BV _{DSS}	$I_D = 250\mu A, V_{GS} = 0$	50	-	-	V
RFP4N06			60	-	-	V
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}$, $I_D = 250\mu$ A, (Figure 8)	2	-	4	V
ro Gate Voltage Drain Current	I _{DSS}	V _{DS} = Rated BV _{DSS} , V _{GS} = 0V	-	-	1	μА
		$V_{DS} = 0.8 \text{ x Rated BV}_{DSS}, V_{GS} = 0 \text{V}, T_{C} = 125^{\circ}\text{C}$	-	-	25	μА
Gate to Source Leakage Current	I _{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0$	-	-	±100	nA
Drain to Source On Resistance (Note 2)	r _{DS(ON)}	I _D = 4A, V _{GS} = 10V, (Figures 6, 7)	-	-	0.800	Ω
Drain to Source On Voltage (Note 2)	V _{DS(ON)}	I _D = 4A, V _{GS} = 10V	-	-	3.2	V
Turn-On Delay Time	t _{d(ON)}	$I_D \approx$ 1A, V_{DD} = 30V, R_{GS} = 50Ω, R_L = 29.2Ω, V_{GS} = 10V, (Figure 10)	-	6	15	ns
Rise Time	t _r		-	14	30	ns
Turn-Off Delay Time	t _{d(OFF)}		-	16	30	ns
Fall Time	t _f		-	14	25	ns
Input Capacitance	C _{ISS}	V _{GS} = 0V, V _{DS} = 25V f = 1MHz, (Figure 9)	-	-	200	pF
Output Capacitance	Coss		-	-	85	pF
Reverse-Transfer Capacitance	C _{RSS}			-	30	pF
Thermal Resistance Junction to Case	$R_{\theta JC}$		-	-	5	°C/W

Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage (Note 2)	V _{SD}	I _{SD} = 1A	-	-	1.4	V
Diode Reverse Recovery Time	t _{rr}	$I_{SD} = 2A$, $dI_{SD}/dt = 50A/\mu s$	-	100	-	ns

NOTES:

- 2. Pulsed test: width $\leq 300 \mu s$ duty cycle $\leq 2\%$.
- 3. Repetitive rating: pulse width limited by maximum junction temperature.

Typical Performance Curves Unless Otherwise Specified

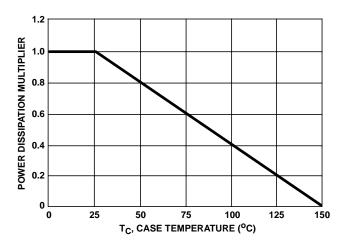


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

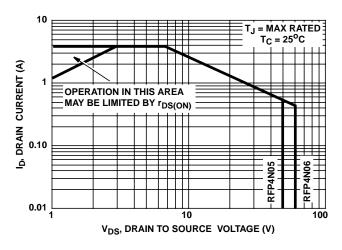


FIGURE 3. FORWARD BIAS SAFE OPERATING AREA

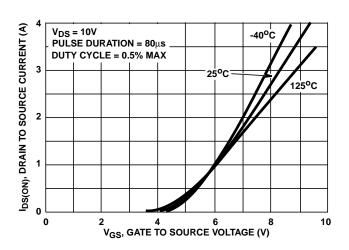


FIGURE 5. TRANSFER CHARACTERISTICS

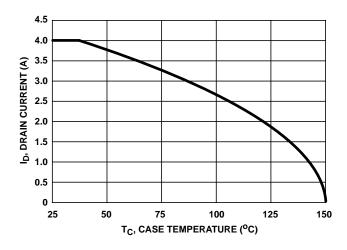


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

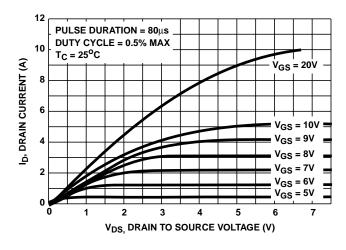


FIGURE 4. SATURATION CHARACTERISTICS

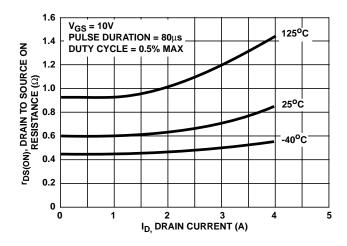


FIGURE 6. DRAIN TO SOURCE ON RESISTANCE vs DRAIN CURRENT

Typical Performance Curves Unless Otherwise Specified (Continued)

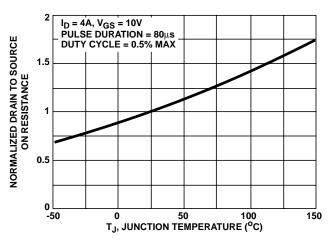


FIGURE 7. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

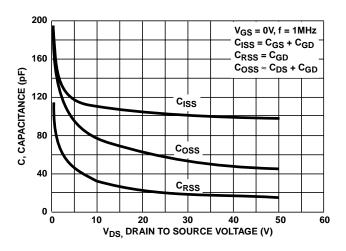


FIGURE 9. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE

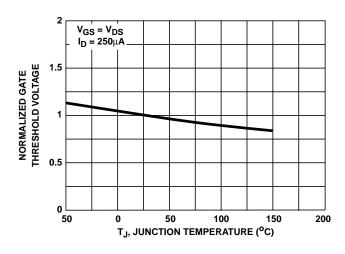
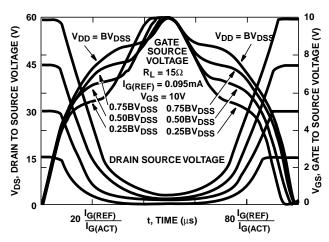


FIGURE 8. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE



NOTE: Refer to Intersil Applications Notes AN7254 and AN7260

FIGURE 10. NORMALIZED SWITCHING WAVEFORMS FOR CONSTANT GATE CURRENT

Test Circuits and Waveforms

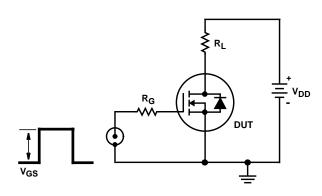


FIGURE 11. SWITCHING TIME TEST CIRCUIT

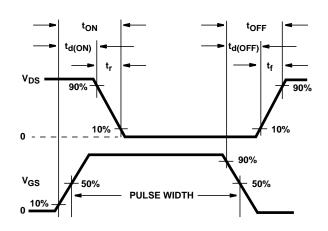


FIGURE 12. RESISTIVE SWITCHING WAVEFORMS

Test Circuits and Waveforms

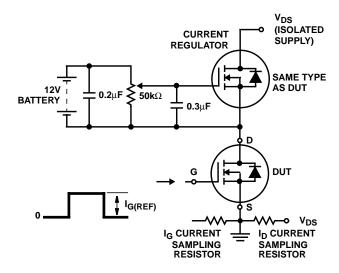


FIGURE 13. GATE CHARGE TEST CIRCUIT

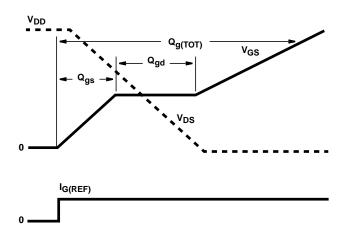


FIGURE 14. GATE CHARGE WAVEFORMS

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